IN THE CLAIMS

All of the claims pending in this application are set forth for the convenience of the Examiner. Please amend the claims as follows:

1-18. (Canceled)

19. (Currently Amended) A method of assembling a multi-chip device comprising:

providing an interposer having a first surface and a second surface;

populating ~~a~~ the second surface of the interposer ~~having a first surface and the second surface~~ with a plurality of conductive pads;

coupling solder balls ~~only to selected ones~~ to only preselected conductive pads of the plurality of conductive pads that are intended to be used, ~~said selected ones~~ the preselected conductive pads being less than all of the plurality of conductive pads;

coupling a plurality of cache memory devices and at least one passive device to the first surface to form a multi-chip subassembly, wherein the at least one passive device is selected from ~~a~~ the group consisting of resistors, capacitors, and inductors;

testing only a portion of ~~the selected ones~~ those conductive pads that have solder balls attached of the plurality of conductive pads on ~~said~~ the interposer;

coupling ~~said~~ the interposer to a substrate with the solder balls and coupling a microprocessor device to the substrate after ~~said~~ the testing if ~~said~~ the plurality of cache memory devices pass ~~said~~ the testing; and

not coupling ~~said~~ the interposer to the substrate and not coupling the microprocessor device to the interposer if ~~said~~ the plurality of cache memory devices does not pass ~~said~~ the testing .

20. (Canceled)

21. (Previously Presented) The method of claim 19 wherein the interposer comprises organic material.

22. (Withdrawn) The method of claim 19 wherein coupling at least one semiconductor die comprises a C4 process.

23. (Canceled)

24. (Withdrawn) The method of claim 19 further comprising coupling a single chip carrier to the substrate.

25. (Withdrawn) The method of claim 19 wherein coupling at least one semiconductor die comprises coupling memory chips to the interposer.

26. (Currently Amended) The method of claim 19, further comprising:

creating a plurality of contacts on the substrate; and

electrically connecting ~~said selected ones~~ the preselected conductive pads of the plurality of conductive pads to the plurality of contacts.

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